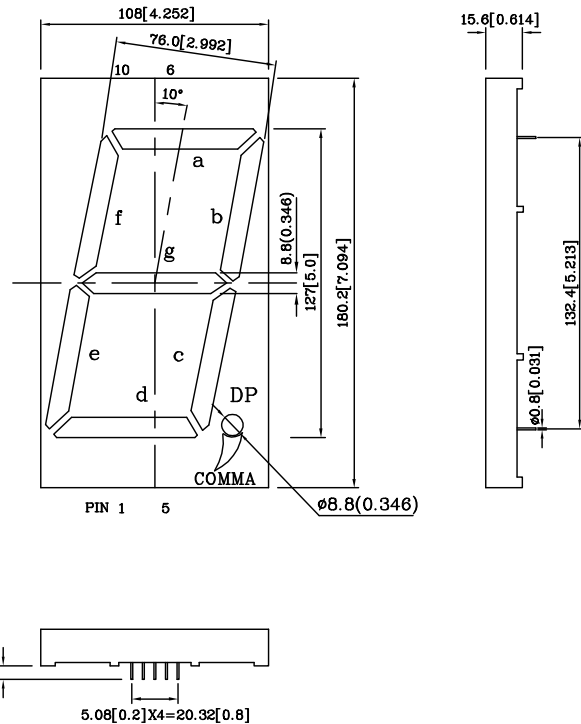
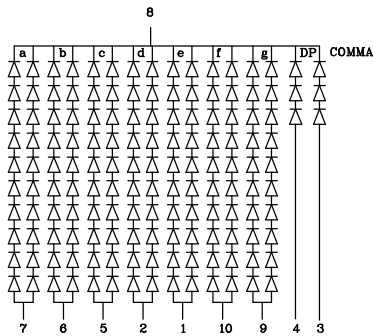


Features

- 5.0 INCH DIGIT HEIGHT.
- LOW CURRENT OPERATION.
- EXCELLENT CHARACTER APPEARANCE.
- EASY MOUNTING ON P.C. BOARDS OR SOCKETS.
- I.C. COMPATIBLE.
- CATEGORIZED FOR LUMINOUS INTENSITY.
- MECHANICALLY RUGGED.
- STANDARD : GRAY FACE, WHITE SEGMENT.
- RoHS COMPLIANT.



Notes:

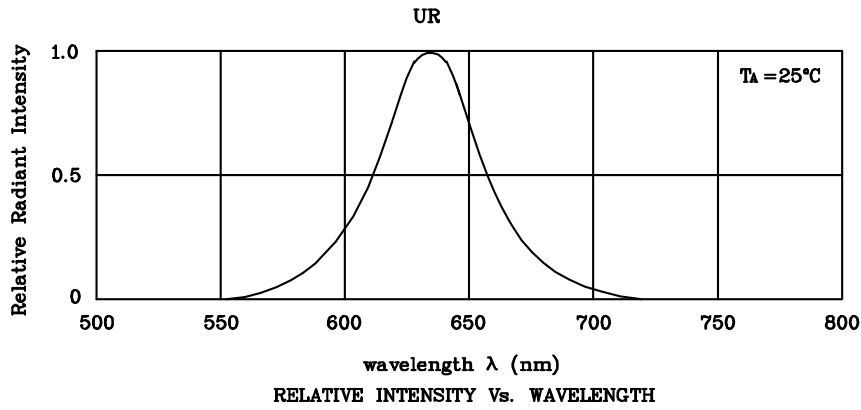
1. All dimensions are in millimeters (inches).
2. Tolerance is $\pm 0.25(0.01")$ unless otherwise noted.
3. Specifications are subject to change without notice.

Absolute Maximum Ratings (TA=25°C)		UR (GaAsP/ GaP)	Unit
Reverse Voltage Per Segment Or (Dp And Comma)	V _R	50 (15)	V
DC Forward Current Per Segment Or (Dp And Comma)	I _F	60 (30)	mA
Forward Current (Peak) Per Segment Or (Dp And Comma) 1/10 Duty Cycle 0.1ms Pulse Width	i _{FS}	320 (160)	mA
Power Dissipation Per Segment Or (Dp And Comma)	P _T	1500 (225)	mW
Operating Temperature	T _A	-40 ~ +85	°C
Storage Temperature	T _{stg}	-40 ~ +85	
Lead Solder Temperature [2mm Below Package Base]	260°C For 3~5 Seconds		

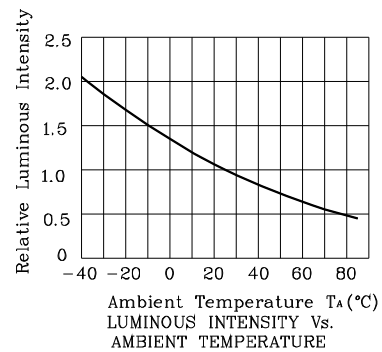
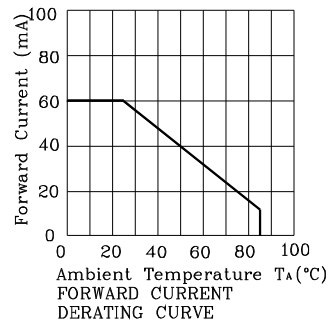
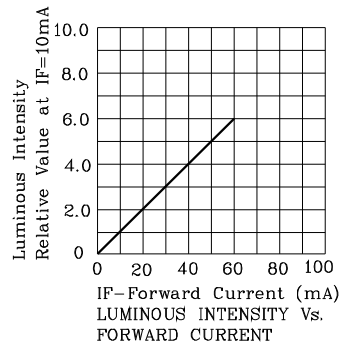
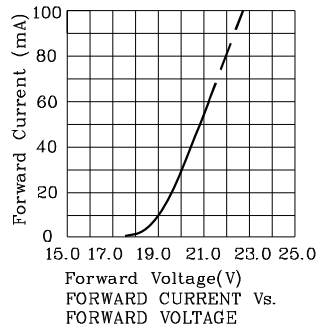
Operating Characteristics (TA=25°C)	UR (GaAsP/ GaP)	Unit
Forward Voltage (I _F =10mA) (Typ.) Per Segment Or (Dp And Comma)	V _F	19.0 (5.7) V
Forward Voltage (I _F =10mA) (Max.) Per Segment Or (Dp And Comma)	V _F	25.0 (7.5) V
Reverse Current (V _R =50V(15V)) (Max.) Per Segment Or (Dp And Comma)	I _R	20 (10) μ A
Wavelength Of Peak Emission (Typ.) (I _F =10mA)	λ P	627 nm
Wavelength Of Dominant Emission (Typ.) (I _F =10mA)	λ D	625 nm
Spectral Line Full Width At Half- Maximum (Typ.) (I _F =10mA)	$\Delta\lambda$	45 nm
Capacitance (Per Segment) (Typ.) (V _F =0V, f=1MHz)	C	15 pF

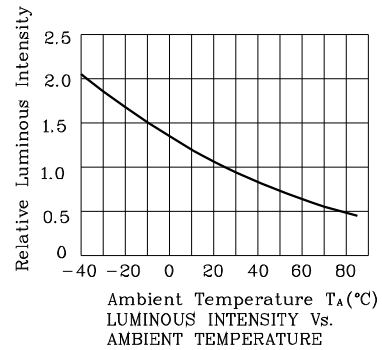
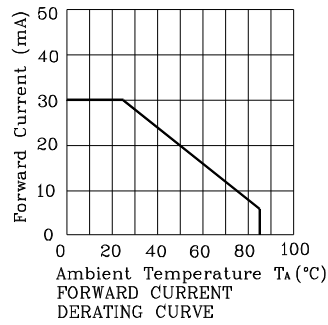
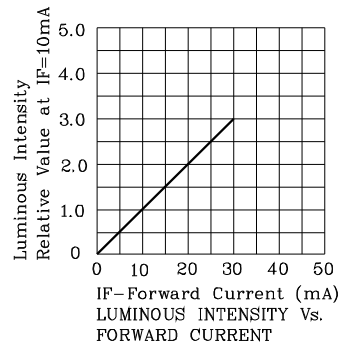
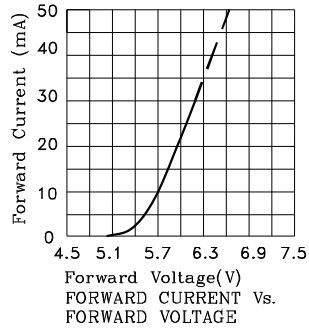


Part Number	Emitting Color	Emitting Material	Luminous Intensity (I _F =10mA) ucd	Wavelength nm λ P	Description
			min.	typ.	
XDUR127C-A	Red	GaAsP/GaP	18000	52290	627 Common Cathode, Rt. Hand Decimal

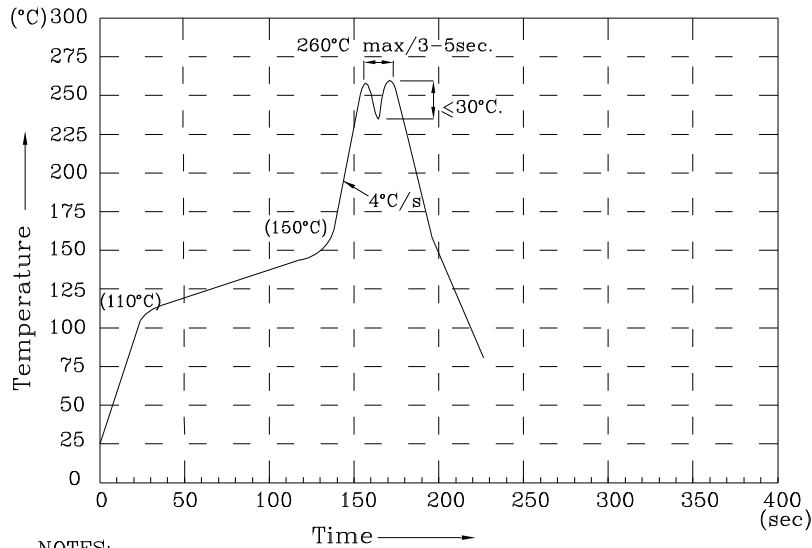


❖ UR





Wave Soldering Profile For Lead-free Through-hole LED.



NOTES:

1. Recommend the wave temperature 245°C~260°C. The maximum soldering temperature should be less than 260°C.
2. Do not apply stress on epoxy resins when temperature is over 85 degree°C.
3. The soldering profile apply to the lead free soldering (Sn/Cu/Ag alloy).
4. No more than once.

Remarks:

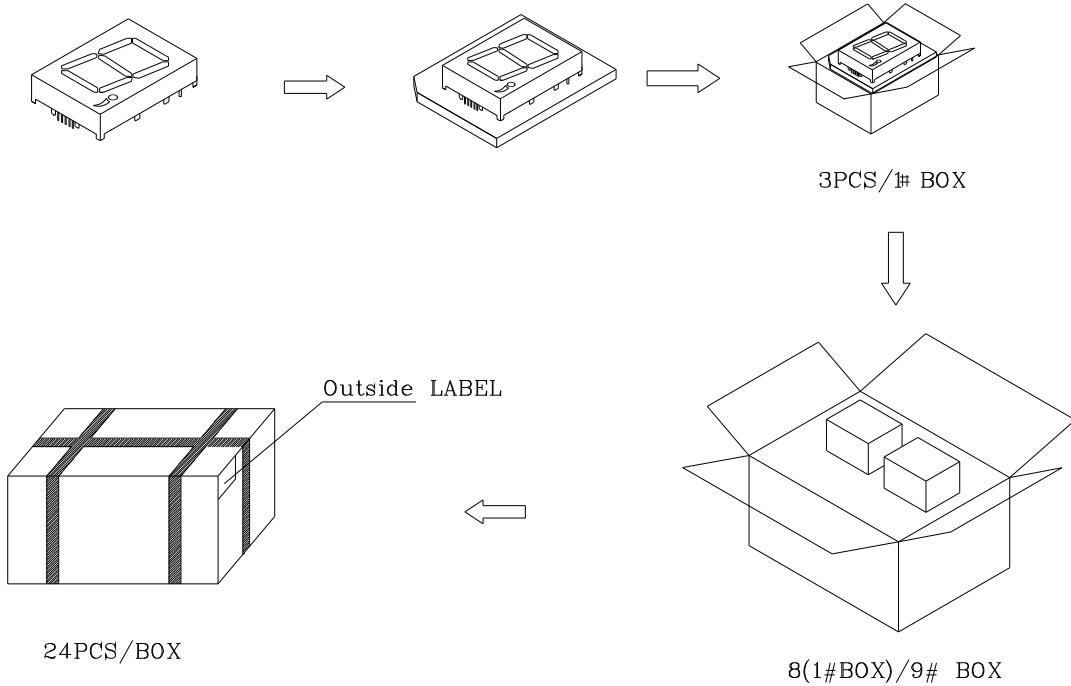
If special sorting is required (e.g. binning based on forward voltage, Luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

1. Wavelength: +/-1nm
2. Luminous intensity / luminous flux: +/-15%
3. Forward Voltage: +/-0.1V

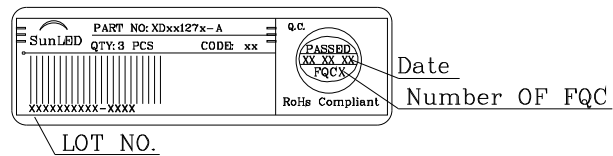
Note: Accuracy may depend on the sorting parameters.

PACKING & LABEL SPECIFICATIONS

XDUR127C-A



Inside LABEL Paste On The 1# Box



Outside LABEL Paste On The Box

